

Data Collection Module Changes List
FCC ID: OBH22250
Date: 07/11/2002

- 1) Hole routed into the PCB inside the PCB trace antenna.
- 2) The dimensions of the PCB antenna were changed to accomodate the smaller PCB size.
- 3) The MSP430 microprocessor package was changed from SOWB-20 to a TSSOP 20 package.
- 4) The board dimensions were reduced by 2mm in length and width.
- 5) An array of holes for programming was changed to a random distribution of test points.
- 6) The orientation and position of capacitors, resistors, transistors and diodes were optimized for manufacturing.
- 7) The position and orientation of the LM77 temperature sensor was changed.
- 8) The position of the 32khz crystal was changed.
- 9) An additional 2uF capacitor was added to the 3V power from the battery.
- 10) The connection of the PCB trace inductor (L2) on the antenna to the ground pour was changed from a plated through hole to a pad.

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